

Customer No.: 31561  
Application No.: 10/064,061  
Docket NO.: 8941-US-PA

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of: )  
Application No.: 10/064,061 )  
Filed: June 6, 2002 )  
For: Flip-Chip Package Substrate )

Applicant: Hsu et al. )  
Examiner: Norris, Jeremy C )  
Art Unit 2827 )

*No fee is believed to be due. However, the Commissioner is authorized to charge any fees required in connection with the filing of this paper to account No. 50-2620 (Order No.: 8941-US-PA)*

U.S. Patent and Trademark Office  
Commissioner for Patents  
2011 South Clark Place  
Customer Window, Mail Stop Non-Fee Amendment  
Crystal Plaza Two, Lobby, Room 1B03  
Arlington, Virginia 22202

**FAX RECEIVED**

JUN 27 2003

TECHNOLOGY CENTER 2800

Sir:

In response to the Office Action dated March 12, 2003, please enter the following amendments and consider the following remarks.

No fee is believed to be due in connection with this amendment and response to Office Action. If, however, any fee is believed to be due, the Commissioner is authorized to charge any fees required in connection with the filing of this paper to account No. 50-2620 (Order No. JCLA8941)

**IN THE CLAIMS**

Please amend the claims as follows.

1. (Currently Amended) A flip-chip package substrate, comprising: